



4Mb PPI MRAM M-die

Parallel Peripheral Interface MRAM

1.8V

- **S3R4016R1M**
- **S3R4008R1M**

Datasheet

NETSOL RESERVES THE RIGHT TO CHANGE PRODUCTS, INFORMATION AND SPECIFICATIONS WITHOUT NOTICE.

Products and specifications discussed herein are for reference purposes only.
All information discussed herein is provided on an "AS IS" basis, without warranties of any kind.

This document and all information discussed herein remain the sole and exclusive property of NETSOL.
No license of any patent, copyright, mask work, trademark or any other intellectual property right is granted by one party to the other party under this document, by implication, estoppel or otherwise.

For updates or additional information about Netsol products, please contact to netsol@netsol.co.kr

Feature

- Interface
 - Parallel Asynchronous and Page Mode Interface
- Page Mode Read Access
 - Interpage read access : 70ns
 - Intrapage read access : 15ns
- Page Mode Write Access
 - Interpage write access : 240ns
 - Intrapage write access : 15ns
- Page Size
 - x16 I/O Mode : 4-word page size
 - x8 I/O Mode : 8-word page size
- Low Power Consumption
 - Read current : 9mA
 - Write current : 14mA
 - Standby current : 185uA
- Data Byte Control(x16 I/O Mode)
 - $\overline{LB}$: DQ₇~DQ₀, $\overline{UB}$: DQ₁₅~DQ₈
- Memory cell : STT-MRAM
 - nonvolatile
- Density
 - 4Mb
- Data Integrity : No external ECC required
- Data Endurance
 - Unlimited read cycle
 - 10¹⁴ write cycles
- Data Retention
 - 10 years at 85°C
- Single Power Supply Operation
 - S3R40xxR1M: 1.71V~1.98V
- Operating Temperature Range
 - Industrial Temperature : -40°C to 85°C
- RoHS compliant packages
 - 44TSOP2 (10 mm x 18 mm)
 - 48FBGA (6 mm x 8 mm)

Performance

Operation	Symbol	Typical Values	Units
Interpage Read Cycle Time	t _{RC}	70(Min.)	ns
Intrapage Read Cycle Time	t _{PRC}	15(Min.)	ns
Interpage Write Cycle Time	t _{WC}	240(Min.)	ns
Intrapage Write Cycle Time	t _{PWC}	15(Min.)	ns
Standby Current	I _{SB}	185	uA
Interpage Read Current	I _{CCR}	9	mA
Intrapage Read Current	I _{CCRP}	9	mA
Interpage Write Current	I _{CCW}	14	mA
Intrapage Write Current	I _{CCWP}	14	mA

Table of Contents

Feature	2
Performance	2
Table of Contents	3
General Description	5
Pin Description – x16 I/O Mode	6
Figure 1 : Functional Block Diagram – x16 I/O mode	6
Table 1 : Pin Description – x16 I/O mode	6
Pin Description – x8 I/O Mode	7
Figure 2 : Functional Block Diagram – x8 I/O mode	7
Table 2 : Pin Description – x8 I/O mode	7
Package Pin Configuration – x16 I/O Mode.....	8
Package Pin Configuration – x8 I/O Mode.....	9
Functional Description	10
Functional Description – x16 I/O Mode	10
Table 5 : Functional Description - x16 I/O mode.....	10
Functional Description – x8 I/O Mode	10
Table 6 : Functional Description - x8 I/O mode	10
Address Pin	10
Table 7 : Address Pin.....	10
Electrical Specifications	11
Absolute Maximum Ratings	11
Table 8 : Absolute Maximum Ratings	11
Endurance, Retention and Magnetic Immunity	11
Table 9 : Endurance, Retention and Magnetic Immunity	11
Recommended Operating Conditions	11
Table 10 : Recommended Operating Conditions	11
Pin Capacitance.....	12
Table 11 : Pin Capacitance.....	12
AC Test Condition.....	12
Table 12 : AC Test Conditions	12
DC Characteristics.....	12
Table 13 : DC Characteristics	12
AC Timing Parameters	13
Table 14 : Read AC Timing Parameter	13
Table 15 : Write AC Timing Parameter	14
Power On/Off Sequence	15
Figure 3 : Power-Up/Down Behavior.....	15
Table 16 : Power-Up/Down Timing	15
Device Operation	16
Read Operation: Interpage	16
Figure 4 : Timing Waveform of Read Cycle : x16 I/O mode.....	16
Figure 5 : Timing Waveform of Read Cycle : x8 I/O mode.....	16
Page Mode Read Operation: Intrapage.....	17
Figure 6 : Timing Waveform of Page Mode Read Cycle : x16 I/O mode.....	17
Figure 7 : Timing Waveform of Page Mode Read Cycle : x8 I/O mode	17
Address Access Read Operation	18
Figure 8 : Timing Waveform of Address Access Read Cycle : x16 I/O mode	18
Figure 9 : Timing Waveform of Address Access Read Cycle : x8 I/O mode	18
Write Operation (WE control): Interpage	19
Figure 10 : Timing Waveform of Write Cycle (WE control) : x16 I/O mode	19
Figure 11 : Timing Waveform of Write Cycle (WE control) : x8 I/O mode	19

Write Operation (CS control): Interpage	20
Figure 12 : Timing Waveform of Write Cycle (CS control) : x16 I/O mode	20
Figure 13 : Timing Waveform of Write Cycle (CS control) : x8 I/O mode	20
Page Mode Write Operation: Intrapage	21
Figure 14 : Timing Waveform of Page Mode Write Cycle : x16 I/O Mode	21
Figure 15 : Timing Waveform of Page Mode Write Cycle : x8 I/O Mode	21
Thermal Resistance	22
Table 17 : Thermal Resistance	22
Part Numbering System	23
Ordering Part Numbers	24
Table 18 : Ordering Part Numbers	24
Package Dimension	25
48 FBGA	25
44 TSOP2	26
Revision History	27

General Description

The device is a Spin-Transfer-Torque Magneto-resistive Random Access Memory (STT-MRAM). Data is always non-volatile and the device can replace FRAM, low-power SRAM or nvSRAM with same functionality and help to simplify system design. Due to the non-volatility and virtually unlimited endurance characteristics of STT-MRAM, it is suited for code storage, data logging, backup memory and working memory in industrial designs.

It is offered in density of 4Mbit. It is a fully random-access memory with parallel asynchronous interface. x16 or x8 I/O mode are supported. And x16 I/O mode allows that lower and upper byte access by data byte control ($\overline{LB}$, $\overline{UB}$).

It supports the asynchronous page mode function to enhance the read and write performance. The page size of x16 I/O mode and x8 I/O mode is 4 words and 8 words.

The S3R4016R1M and S3R4008R1M are packaged in industrial standard 44TSOP2 and 48FBGA. These packages are compatible with similar low-power volatile and non-volatile products. The device is offered with industrial (-40°C to 85°C) operating temperature range.

Pin Description – x16 I/O Mode

Figure 1 : Functional Block Diagram – x16 I/O mode

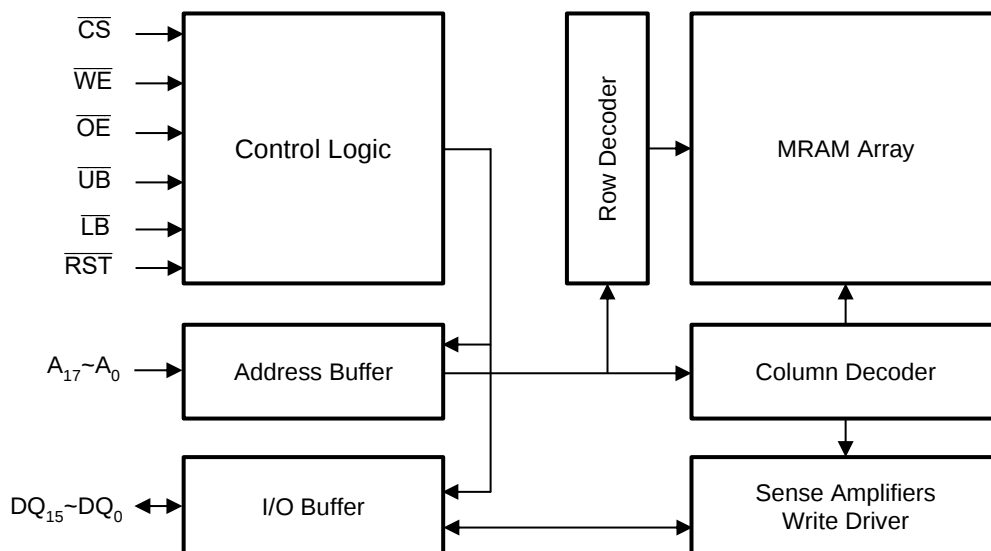


Table 1 : Pin Description – x16 I/O mode

Pin	Type	Description
$\overline{CS}$	Input	Chip Select: When $\overline{CS}$ is driven Low, read or write operation are initiated. When $\overline{CS}$ is driven High, the device enters standby mode, and all other input pins are ignored and the output pins are tri-stated. $\overline{CS}$ should be High at power-up to prevent abnormal write operation. This pin does not have internal pullup resistor.
$\overline{WE}$	Input	Write Enable: When $\overline{CS}$ and $\overline{WE}$ are driven Low, write operation is initiated. The rising edge of $\overline{CS}$ causes the device to transfer the data to memory array. The rising edge of $\overline{WE}$ latches the input data. And, the falling edge of $\overline{WE}$ latches a new page address for write cycles.
$\overline{OE}$	Input	Output Enable
LB	Input	Lower Byte Control: DQ ₇ ~DQ ₀
UB	Input	Upper Byte Control: DQ ₁₅ ~DQ ₈
A ₁₇ ~A ₀	Input	Address The LSB address A ₁ ~A ₀ are used for page mode read and write operation.
DQ ₁₅ ~DQ ₀	Bidirectional	Data Input/Outputs
$\overline{RST}$	Input	Reset $\overline{RST}$ pin is a hardware RESET signal. When $\overline{RST}$ is driven High, the device is in the normal operation mode. When $\overline{RST}$ is driven Low, the device enters in the initialization mode. This pin has an internal pullup resistor.
Vcc	Supply	Power pin
Vss	Supply	Ground pin
NC	-	Not Connected
DNU	-	Do Not Use : DNUs must be left unconnected.

Pin Description – x8 I/O Mode

Figure 2 : Functional Block Diagram – x8 I/O mode

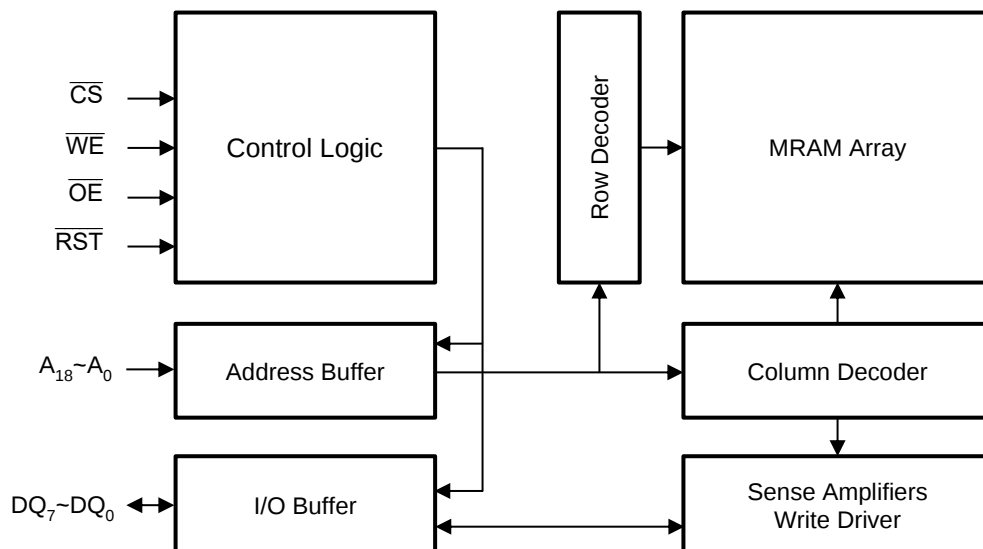


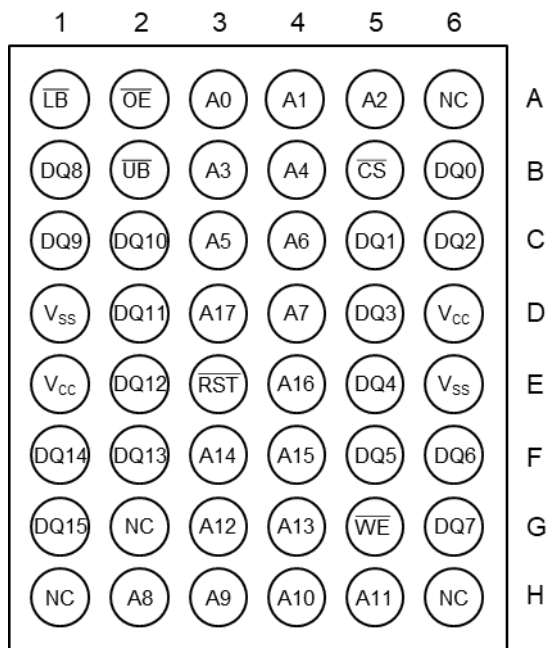
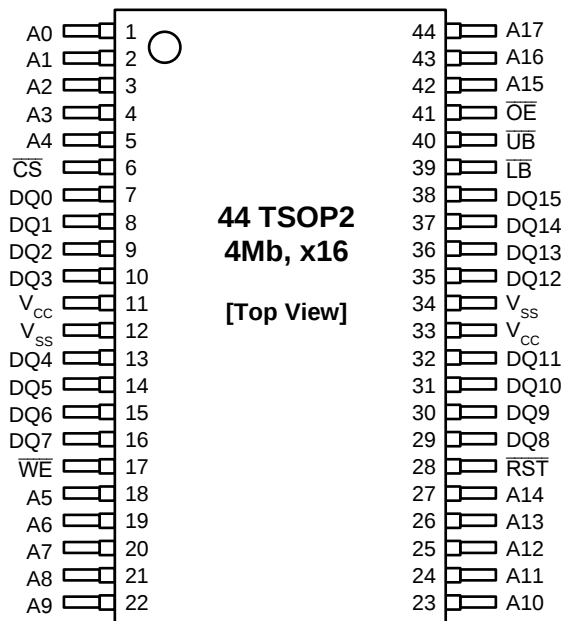
Table 2 : Pin Description – x8 I/O mode

Pin	Type	Description
$\overline{CS}$	Input	Chip Select: When $\overline{CS}$ is driven Low, read or write operation are initiated. When $\overline{CS}$ is driven High, the device enters standby mode, and all other input pins are ignored and the output pins are tri-stated. $\overline{CS}$ should be High at power-up to prevent abnormal write operation. This pin does not have internal pullup resistor.
$\overline{WE}$	Input	Write Enable: When $\overline{CS}$ and $\overline{WE}$ are driven Low, write operation is initiated. The rising edge of $\overline{CS}$ causes the device to transfer the data to memory array. The rising edge of $\overline{WE}$ latches the input data. And, the falling edge of $\overline{WE}$ latches a new page address for write cycles.
$\overline{OE}$	Input	Output Enable
$A_{18} \sim A_0$	Input	Address The LSB address $A_2 \sim A_0$ are used for page mode read and write operation.
$DQ_7 \sim DQ_0$	Bidirectional	Data Input/Outputs
$\overline{RST}$	Input	Reset $\overline{RST}$ pin is a hardware RESET signal. When $\overline{RST}$ is driven High, the device is in the normal operation mode. When $\overline{RST}$ is driven Low, the device enters in the initialization mode. This pin has an internal pullup resistor.
Vcc	Supply	Power pin
Vss	Supply	Ground pin
NC	-	Not Connected
DNU	-	Do Not Use : DNUs must be left unconnected.

Package Pin Configuration – x16 I/O Mode

48 Ball FBGA(4Mb, x16)

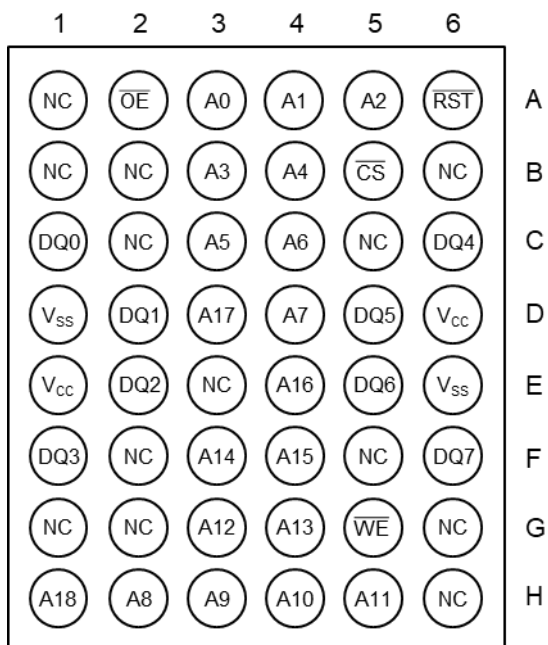
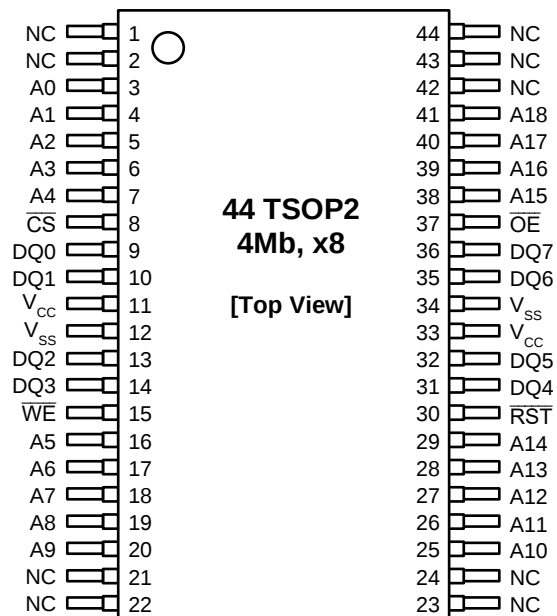
[Top View]



Package Pin Configuration – x8 I/O Mode

48 Ball FBGA(4Mb, x8)

[Top View]



Functional Description

Functional Description – x16 I/O Mode

Table 5 : Functional Description - x16 I/O mode

CS	WE	OE	LB	UB	DQ ₇ ~DQ ₀	DQ ₁₅ ~DQ ₈	Modes	Supply Current
H	X	X	X	X	High-Z	High-Z	Not Selected	I _{SB}
L	H	H	X	X	High-Z	High-Z	Output disable	I _{CCR}
L	H	L	H	H	High-Z	High-Z	Output disable	I _{CCR}
L	H	L	L	H	Dout	High-Z	Lower Byte Read	I _{CCR}
L	H	L	H	L	High-Z	Dout	Upper Byte Read	I _{CCR}
L	H	L	L	L	Dout	Dout	Word Read	I _{CCR}
L	L	X	H	H	High-Z	High-Z	Input disable	I _{CCW}
L	L	X	L	H	Din	High-Z	Lower Byte Write	I _{CCW}
L	L	X	H	L	High-Z	Din	Upper Byte Write	I _{CCW}
L	L	X	L	L	Din	Din	Word Write	I _{CCW}

Functional Description – x8 I/O Mode

Table 6 : Functional Description - x8 I/O mode

CS	WE	OE	DQ ₇ ~DQ ₀	Modes	Supply Current
H	X	X	High-Z	Not Selected	I _{SB}
L	H	H	High-Z	Output disable	I _{CCR}
L	H	L	Dout	Word Read	I _{CCR}
L	L	X	Din	Word Write	I _{CCW}

Notes:

1. H = High, L = Low, X = don't care, High-Z : high impedance

Address Pin

Table 7 : Address Pin

Density	Address Pin x16 I/O mode	Address Pin x8 I/O mode
4Mb	A[17:0]	A[18:0]

Parameter	x16 I/O mode	x8 I/O mode
Page Address	A ₁ ~A ₀	A ₂ ~A ₀

Electrical Specifications

Absolute Maximum Ratings

Stresses greater than those listed may cause permanent damage to the device. This is a stress rating only. Exposure to maximum rating for extended periods may adversely affect reliability.

Table 8 : Absolute Maximum Ratings

Parameter	Min.	Max.	Units
Voltage on Vcc Supply Relative to VSS	-0.5	2.35	V
Voltage on Any Pin relative to VSS	-0.5	2.35	V
Storage Temperature	-55	150	°C
Operating Ambient Temperature	-40	85	°C
ESD HBM (Human Body Model)	≥ 2000 V		V
ESD CDM (Charged Device Model)	≥ 500 V		V
Solder Reflow Process	JEDEC J-STD-020 reflow profiles - Peak temperature ≤ 260°C - The time above 255°C ≤ 30 seconds - Reflow cycles ≤ 3 times		

Endurance, Retention and Magnetic Immunity

Table 9 : Endurance, Retention and Magnetic Immunity

Parameter	Conditions	Min.	Max.	Units
Write Endurance	-25°C	10 ¹⁴	-	Cycles/page
Data Retention	85°C	10	-	years
Magnetic Field During Write or Read	-	-	24,000	A/m

Recommended Operating Conditions

Table 10 : Recommended Operating Conditions

Parameter / Condition	Min.	Typ.	Max.	Units
Operating Temperature	-40	25	85	°C
Vcc Supply Voltage	1.71	1.8	1.98	V
Vss Supply Voltage	0.0	0.0	0.0	V

Pin Capacitance

Table 11 : Pin Capacitance

Parameter	Conditions	Typ.	Max.	Units
Input Pin Capacitance	TEMP = 25°C; f = 1 MHz; $V_{IN} = 0V$	-	4	pF
Input/Output Pin Capacitance	TEMP = 25°C; f = 1 MHz; $V_{I/O} = 0V$	-	6	pF

* Capacitance is sampled and not 100% tested

AC Test Condition

Table 12 : AC Test Conditions

Parameter	Value
Input pulse levels	0.0V to V_{CC}
Input rise and fall times	1ns/1V
Input and output measurement timing levels	$V_{CC}/2$
Output Load	CL = 30pF

DC Characteristics

Table 13 : DC Characteristics

Parameters	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Leakage Current	I_{LI}	$V_{IN} = V_{SS}$ to V_{CC}	-2	-	+2	uA
Output Leakage Current	I_{LO}	$\overline{CS}=V_{IH}$ or $\overline{OE}=V_{IH}$ or $\overline{WE}=V_{IL}$ $V_{OUT} = V_{SS}$ to V_{CC}	-2	-	+2	uA
Read Current	Random	I_{CCR} $V_{CC} (max)$, $I_{OUT}=0mA$	-	9	13	mA
	Page mode	I_{CCRP} $V_{CC} (max)$, $I_{OUT}=0mA$	-	9	13	mA
Write Current	Random	I_{CCW} $V_{CC} (max)$	-	14	18	mA
	Page mode	I_{CCWP} $V_{CC} (max)$	-	14	18	mA
Standby Current	I_{SB}	$V_{CC} (max)$, $\overline{CS} \geq V_{CC}-0.2V$	-	185	330	uA
Input High Voltage	V_{IH}	-	$0.7 \times V_{CC}$	-	$V_{CC}+0.3$	V
Input Low Voltage	V_{IL}	-	-0.3	-	$0.3 \times V_{CC}$	V
Output High Voltage	V_{OH}	$I_{OH}=-1mA$	1.4	-	-	V
Output Low Voltage	V_{OL}	$I_{OL}=2mA$	-	-	0.4	V

AC Timing Parameters

Table 14 : Read AC Timing Parameter

Parameter	Symbol	Min.	Max.	Units
Read Cycle Time (Interpage)	t_{RC}	70	-	ns
Page Read Cycle Time (Intrapage)	t_{PRC}	15	-	ns
$\overline{CS}$ Read Active Time	t_{RCA}	65	-	ns
$\overline{CS}$ Falling to Valid Output Time	t_{CO}	-	65	ns
Address Access Time ²⁾	t_{AA}	-	80	ns
Page Address Access Time	t_{PAA}	-	15	ns
$\overline{CS}$ Rising to Output Hold Time	t_{COH}	3	-	ns
Address change to Output Hold Time ²⁾	t_{OH}	30	-	ns
Page address change to Output Hold Time	t_{POH}	5	-	ns
$\overline{OE}$ Falling to Valid Output Time	t_{OE}	-	15	ns
$\overline{UB}$, $\overline{LB}$ Falling to Valid Output Time ¹⁾	t_{BA}	-	15	ns
$\overline{CS}$ Rising to High-Z Output Time	t_{CHZ}	-	8	ns
$\overline{OE}$ Rising to High-Z Output Time	t_{OHZ}	-	8	ns
$\overline{UB}$, $\overline{LB}$ Rising to High-Z Output Time ¹⁾	t_{BHZ}	-	8	ns
Address Transition to $\overline{CS}$ falling Time ²⁾	t_{CAS}	0	-	ns
$\overline{CS}$ Rising to Address Transition Time ²⁾	t_{CAH}	0	-	ns
$\overline{WE}$ Rising to $\overline{CS}$ Falling Time	t_{WES}	0	-	ns
$\overline{CS}$ Rising to $\overline{WE}$ Falling Time	t_{WEH}	0	-	ns
$\overline{CS}$ High Time for Read End	t_{CSDR}	5	-	ns
Address Transition Interval Time	t_{AX}	-	5	ns

Notes:

- Those parameters are applied for x16 I/O mode only.
- Address except for page address

AC Timing Parameters

Table 15 : Write AC Timing Parameter

Parameters	Symbol	Min	Max	Unit
Write Cycle Time (Interpage)	t_{WC}	240	-	ns
$\overline{CS}$ Write Active Time ³⁾	t_{WCA}	20	-	ns
$\overline{CS}$ Falling to End of Write Time	t_{CW}	20	-	ns
Page Write Cycle Time (Intrapage)	t_{PWC}	15	-	ns
$\overline{WE}$ Falling to End of Write (invalid output does not appear)	t_{WP}	10	-	ns
$\overline{WE}$ Falling to End of Write (invalid output appears)	t_{WP1}	20	-	ns
$\overline{UB}$, $\overline{LB}$ Falling to End of Write Time ¹⁾	t_{BW}	10	-	ns
$\overline{WE}$ Falling to Output High-Z Time	t_{WHZ}	-	8	ns
Valid Input Data to End of Write Time	t_{DS}	8	-	ns
End of Write to Valid Input Data Time	t_{DH}	0	-	ns
Address Transition Time to $\overline{CS}$ falling ²⁾	t_{CAS}	0	-	ns
$\overline{CS}$ Rising to Address Transition Time ²⁾	t_{CAH}	0	-	ns
Page Address Transition to $\overline{WE}$ falling Time	t_{PAS}	0	-	ns
$\overline{WE}$ falling to Page Address Transition Time	t_{PAH}	10	-	ns
$\overline{WE}$ High Time for Page Write	t_{PWH}	3	-	ns
$\overline{CS}$ High Time for Write End ³⁾	t_{CSDW}	180	-	ns

Notes:

- Those parameters are applied for x16 I/O mode only.
- Address except for page address
- $t_{WCA} + t_{CSDW} \geq t_{WC}$

Power On/Off Sequence

- When power-up, power-down or power-loss, $\overline{CS}$ must follow V_{CC} to provide data protection.
- It is recommended that $\overline{CS}$ must follow V_{CC} when V_{CC} is below $V_{CC}(\text{minimum})$ and during t_{PU} .
- A 10K Ω pull-up resistor between V_{CC} and $\overline{CS}$ pin is recommended.
- Reset operation is required after t_{PU} .
- Normal operation must start after t_{RST} .

Figure 3 : Power-Up/Down Behavior

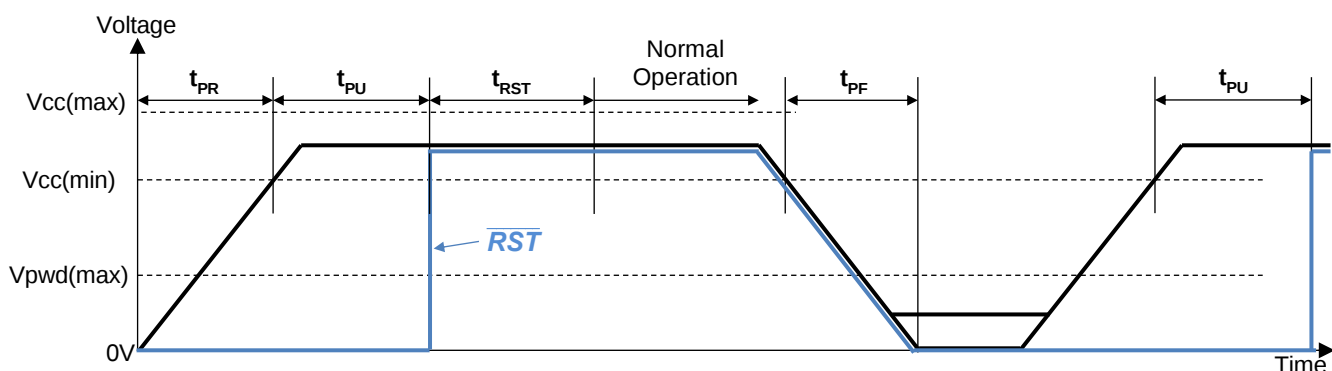


Table 16 : Power-Up/Down Timing

Parameter	Symbol	Min	Max	Units
Vcc Range	VCC	1.71	1.98	V
Vcc rising time	$t_{PR}^{(1)}$	30	-	$\mu\text{s/V}$
Vcc falling time	$t_{PF}^{(1)}$	30	-	$\mu\text{s/V}$
Vcc(min) to $\overline{CS}$ Low (first instruction) time	$t_{PU}^{(1)}$	1.0	-	ms
$\overline{RST}$ High to $\overline{CS}$ Low (first instruction) time	$t_{RST}^{(1)}$	2.0	-	ms
Vcc needed to below Vpwd for ensuring initialization will occur	$V_{PWD}^{(1)}$	-	0.8	V
Reset Time	$t_{RST}^{(1)}$	2.0	-	ms

Notes:

1: These parameters are guaranteed by characterization; not tested in production.

Device Operation

Read Operation: Interpage

Read operation is initiated when $\overline{CS}$ goes to low and $\overline{WE}$ is high. The falling edge of $\overline{CS}$ latches the address and starts to read data from memory array. The output data are available after t_{CO} . The minimum random read cycle time is t_{RC} . The data remains in High-Z until the valid data is output.

Figure 4 : Timing Waveform of Read Cycle : x16 I/O mode

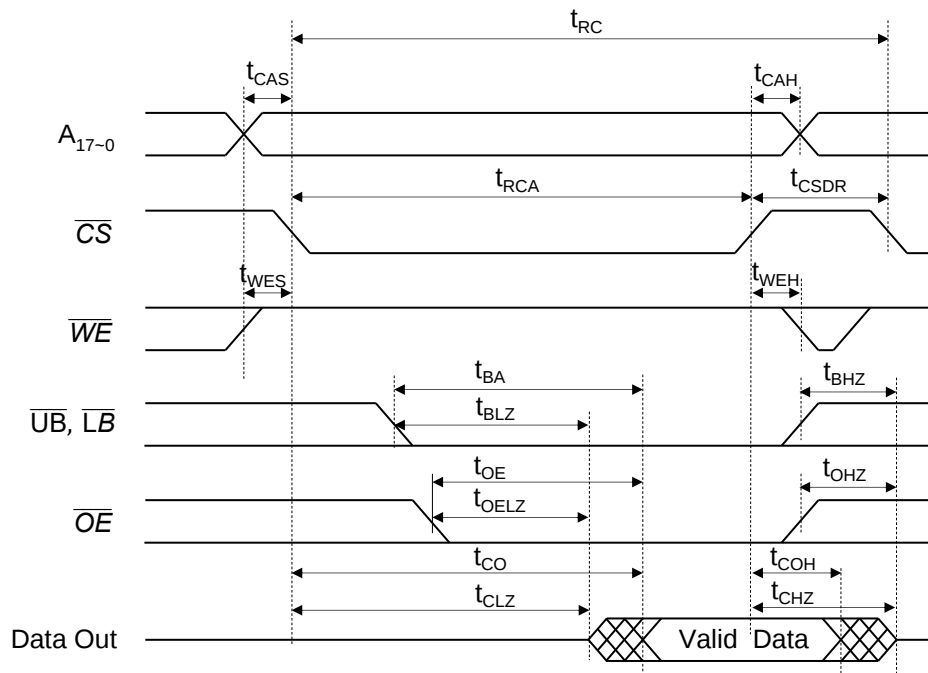
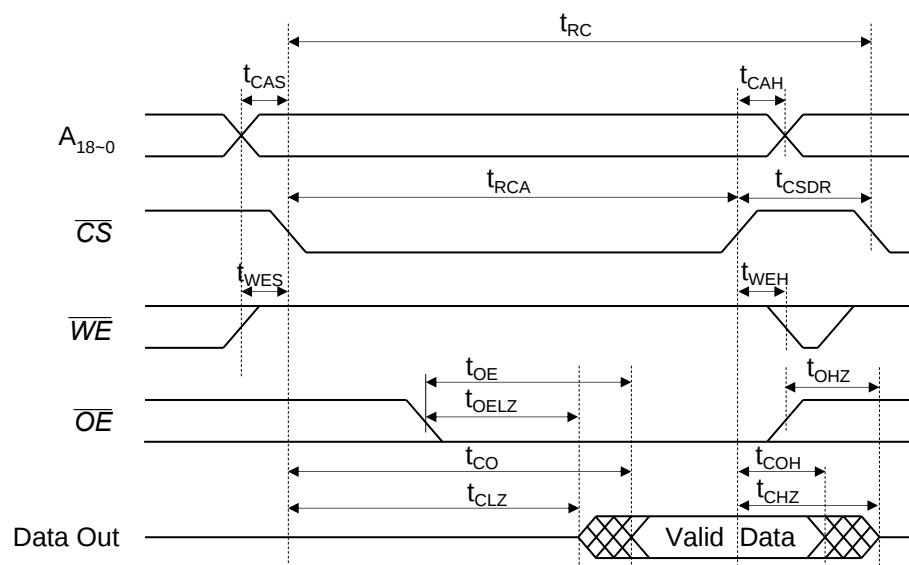


Figure 5 : Timing Waveform of Read Cycle : x8 I/O mode



Page Mode Read Operation: Intrapage

The device supports the page mode read function to enhance the read performance. It reads a page data from memory array and latches the data into an internal page buffer.

The first data is output after t_{CO} . When the next page address is input, subsequent data is output from the page buffer after t_{PAA} .

The sequence and length of page address are not restricted.

For example, the sequence A2-A0-A1 is available.

Parameter	x16 I/O mode	x8 I/O mode
Page Address	A ₁ ~A ₀	A ₂ ~A ₀
Page size	4-word (8-bytes)	8-word (8-bytes)

Figure 6 : Timing Waveform of Page Mode Read Cycle : x16 I/O mode

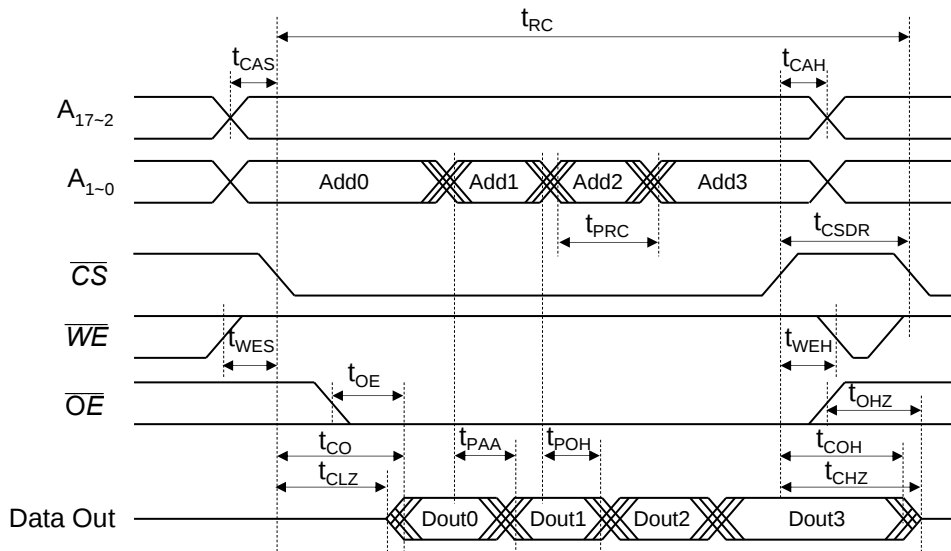
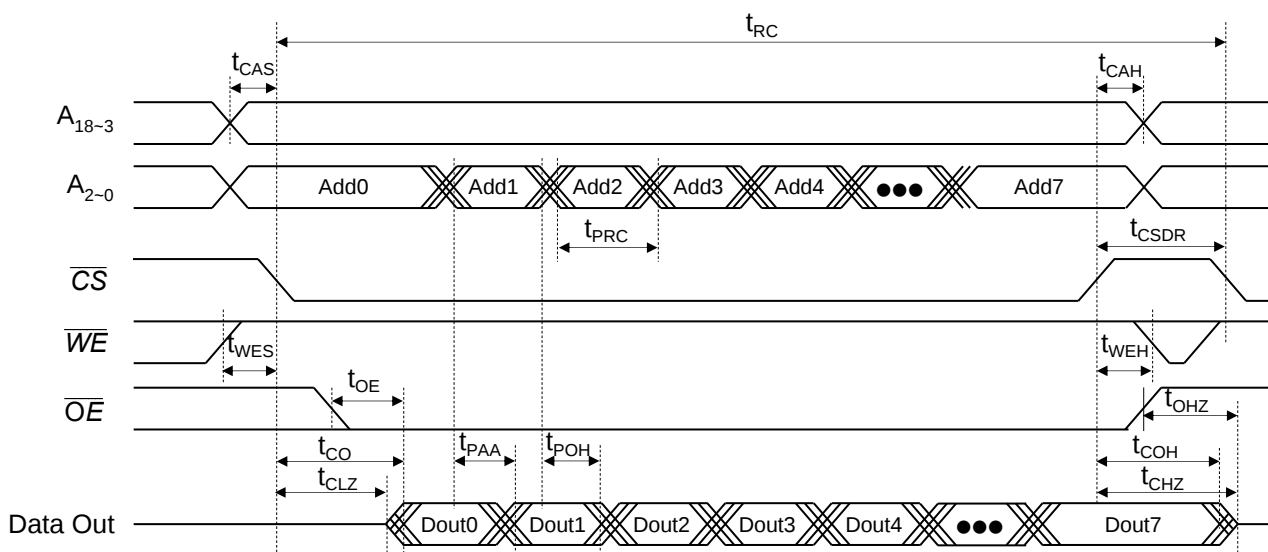


Figure 7 : Timing Waveform of Page Mode Read Cycle : x8 I/O mode



Address Access Read Operation

During $\overline{CS}$ is low and $\overline{WE}$ is high, if a random address (except for the page address) are changed, the device reads a page data from memory array of a new address and latches the data into an internal page buffer. The first data is output after t_{AA} . When the next page address is input, subsequent data is output from the page buffer after t_{PAA} . The random address transition time should not exceed t_{AX} .

Figure 8 : Timing Waveform of Address Access Read Cycle : x16 I/O mode

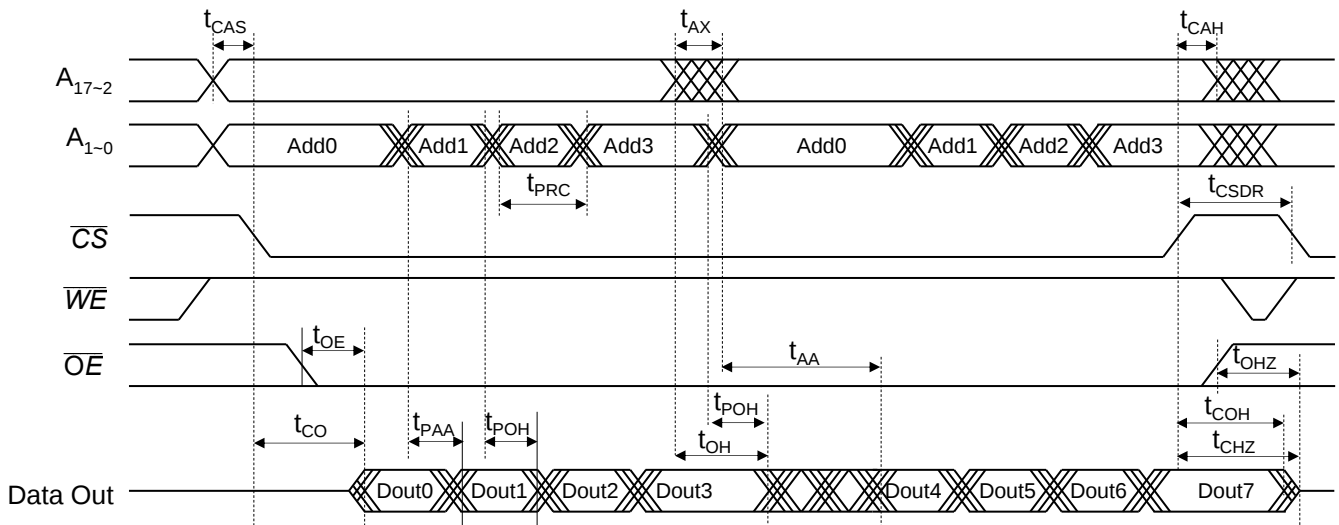
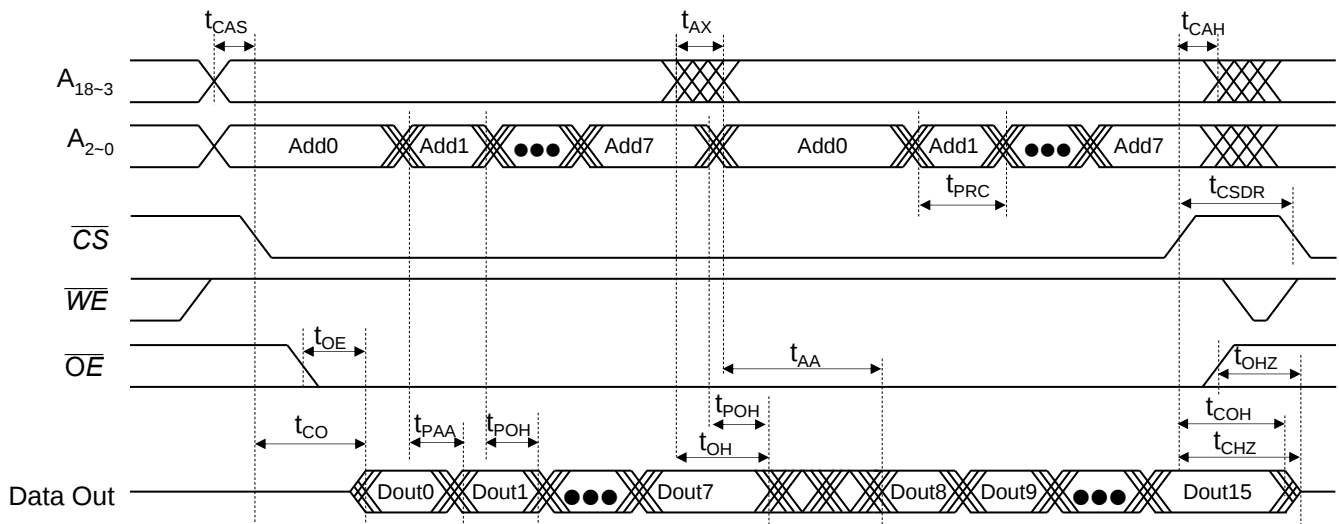


Figure 9 : Timing Waveform of Address Access Read Cycle : x8 I/O mode



Write Operation ($\overline{WE}$ control): Interpage

Write operation is initiated when $\overline{WE}$ goes to low and $\overline{CS}$ is low. The device latches address on the falling edge of $\overline{CS}$. It latches the lower byte data on the rising edge of $\overline{WE}$ or $\overline{LB}$ and the upper byte data on the rising edge of $\overline{WE}$ or $\overline{UB}$ for x16 I/O mode.

It latches the data on the rising edge of $\overline{WE}$ for x8 I/O mode. The rising edge of $\overline{CS}$ causes the device to transfer the input data to memory array.

Figure 10 : Timing Waveform of Write Cycle ($\overline{WE}$ control) : x16 I/O mode

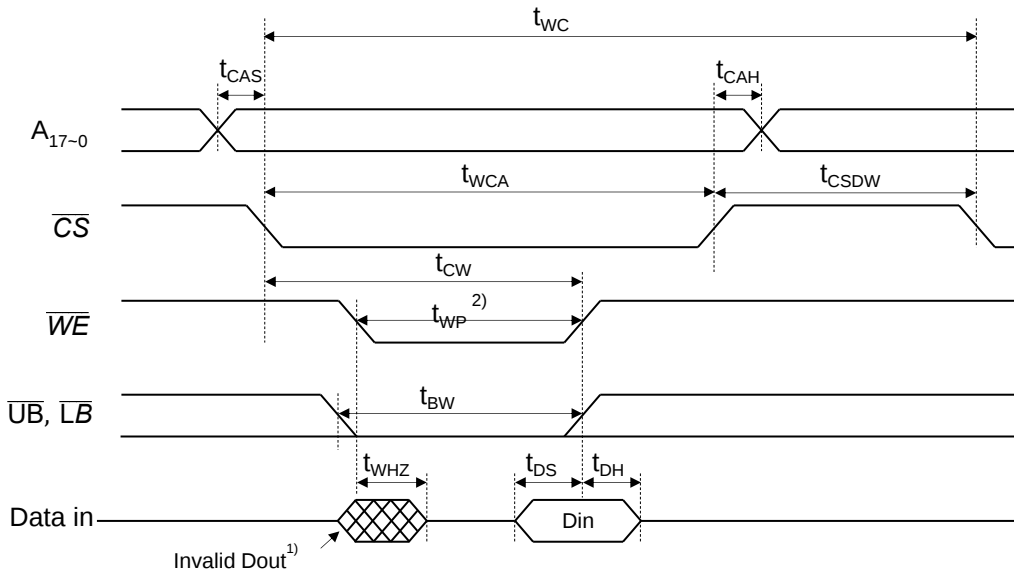
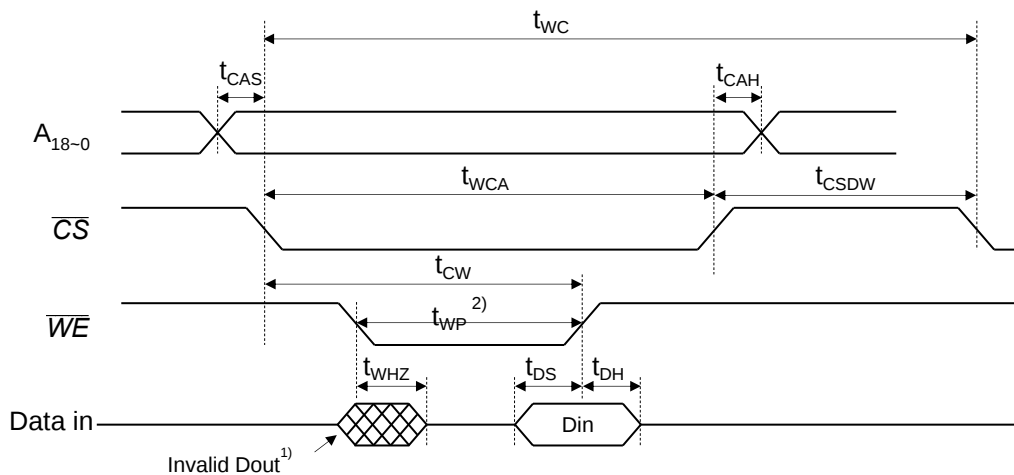


Figure 11 : Timing Waveform of Write Cycle ($\overline{WE}$ control) : x8 I/O mode



Notes :

1. The data pins remain in High-Z state if the time of $\overline{CS}$ falling to $\overline{WE}$ falling is smaller than 30ns or $\overline{OE}$ is High.
2. In case that the data pins do not remains in High-Z state, t_{WP} should be t_{WP1}
3. $t_{WCA} + t_{CSDW} \geq t_{WC}$

Write Operation ($\overline{CS}$ control): Interpage

Write operation is initiated when $\overline{CS}$ goes to low and $\overline{WE}$ is low. The device latches address on the falling edge of $\overline{CS}$. It latches the lower byte data on the rising edge of $\overline{CS}$ or $\overline{LB}$ and the upper byte data on the rising edge of $\overline{CS}$ or $\overline{UB}$ for x16 I/O mode.

It latches the data on the rising edge of $\overline{CS}$ for x8 I/O mode. The rising edge of $\overline{CS}$ causes the device to transfer the input data to memory array.

Figure 12 : Timing Waveform of Write Cycle ($\overline{CS}$ control) : x16 I/O mode

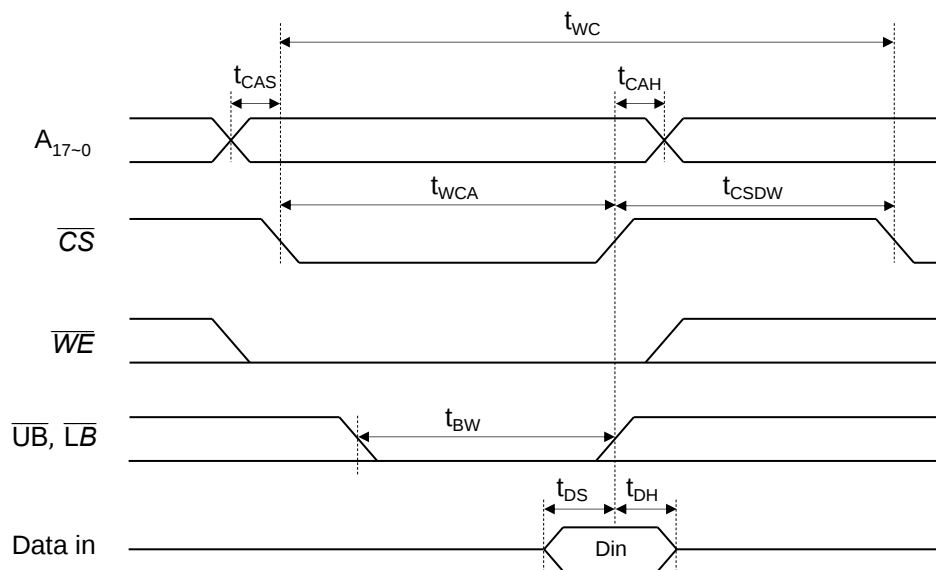
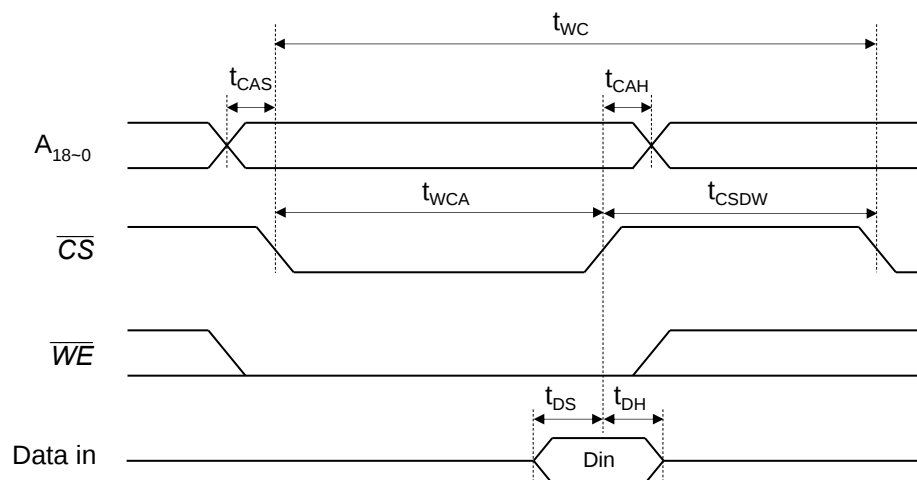


Figure 13 : Timing Waveform of Write Cycle ($\overline{CS}$ control) : x8 I/O mode



Page Mode Write Operation: Intrapage

The device supports the page mode write function to enhance the write performance. It latches a page address every falling edge of $\overline{WE}$.

It latches the lower byte data on every rising edge of $\overline{WE}$ or $\overline{LB}$ and the upper byte data on every rising edge of $\overline{WE}$ or $\overline{UB}$ for x16 I/O mode.

It latches the data on every rising edge of $\overline{WE}$ for x8 I/O mode. The rising edge of $\overline{CS}$ causes the device to transfer the input data to memory array.

The sequence and length of page address are not restricted. For example, the sequence A2-A0-A1 is available.

Figure 14 : Timing Waveform of Page Mode Write Cycle : x16 I/O Mode

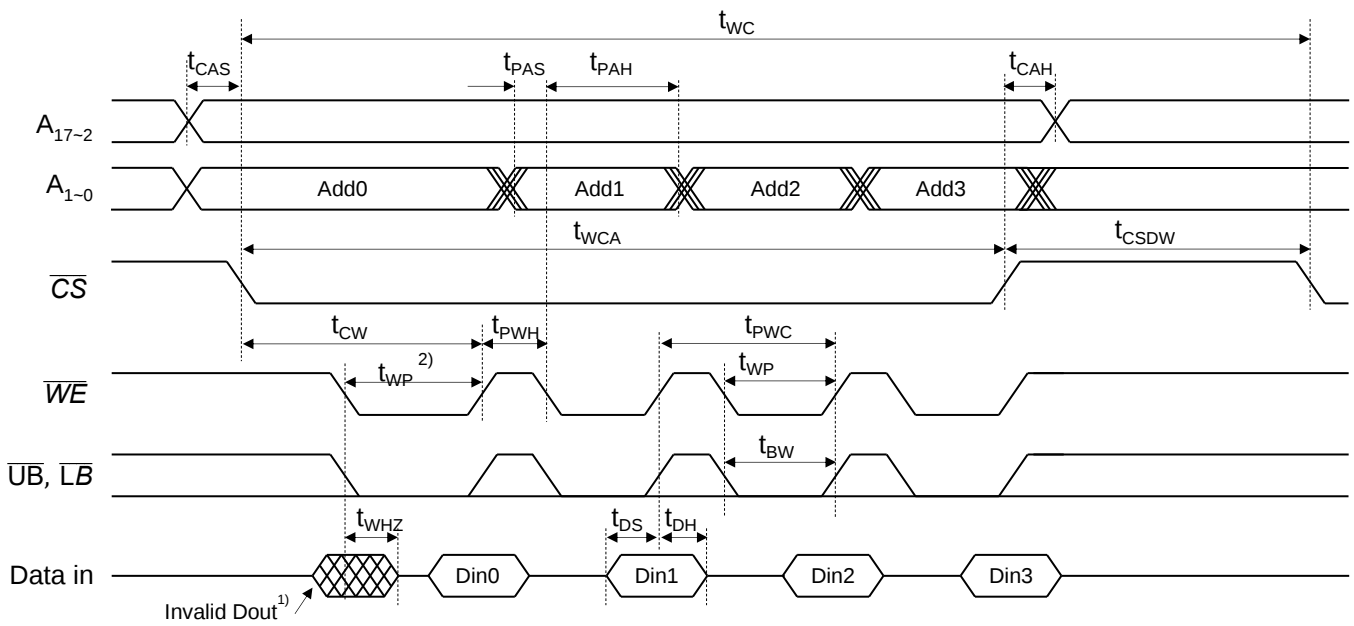
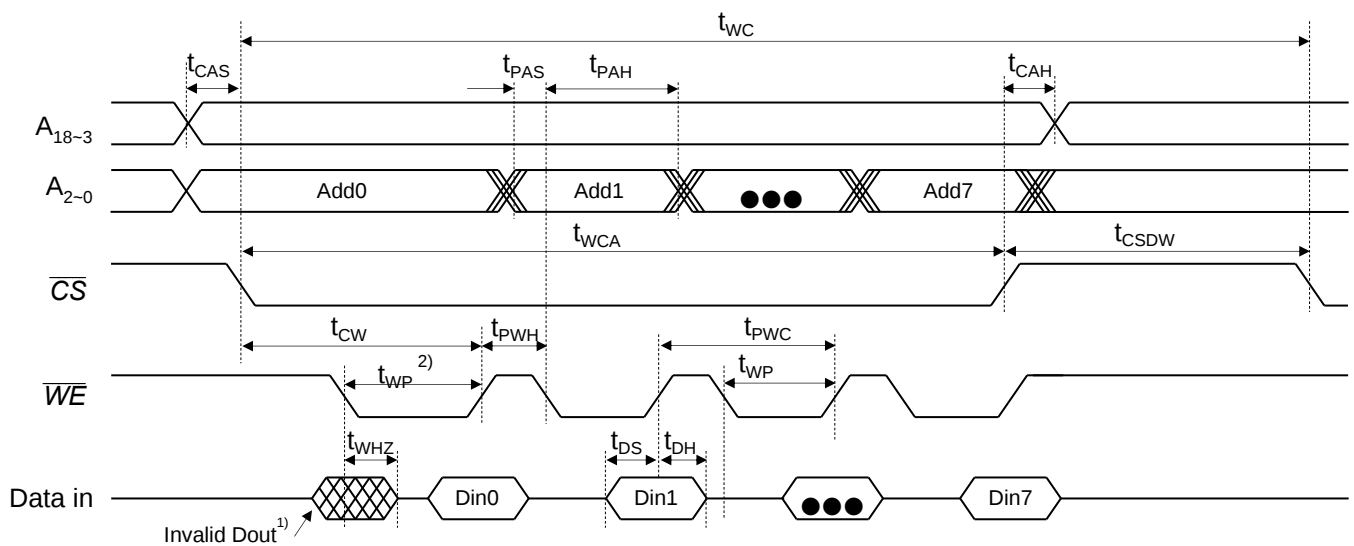


Figure 15 : Timing Waveform of Page Mode Write Cycle : x8 I/O Mode



Thermal Resistance

Table 17 : Thermal Resistance

Parameter	Description	48FBGA	44TSOP2	Unit
θ_{JA}	Thermal resistance (junction to ambient)	69.4	65.2	°C/W
θ_{JC}	Thermal resistance (junction to case)	31.1	15.9	

Notes:

1: These parameters are guaranteed by characterization; not tested in production

Part Numbering System

S	3	R	x	x	x	x	x	x	x	-	x	x	x	x	x	x	x
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

**Netsol
Memory : S**

MRAM : 3

**Async Parallel
Interface : R**

Density
1Mb : 10, 2Mb : 20
4Mb : 40, 8Mb : 80
16Mb : 16, 32Mb : 32
64Mb : 64

I/O Organization
x8 : 08
x16 : 16

VCC
2.70~3.60V : V
1.71~1.98V : R

CS pin option
1CS pin : 1

**Special Code
by customer request**
Default : 00

Packing Material
Tray : 0 T&R : T

Speed
70ns : 70

Temperature
Commercial : C
Industrial : I

Package
44TSOP2 : U
54TSOP2 : P
48FBGA : X

Generation
1st Generation : M

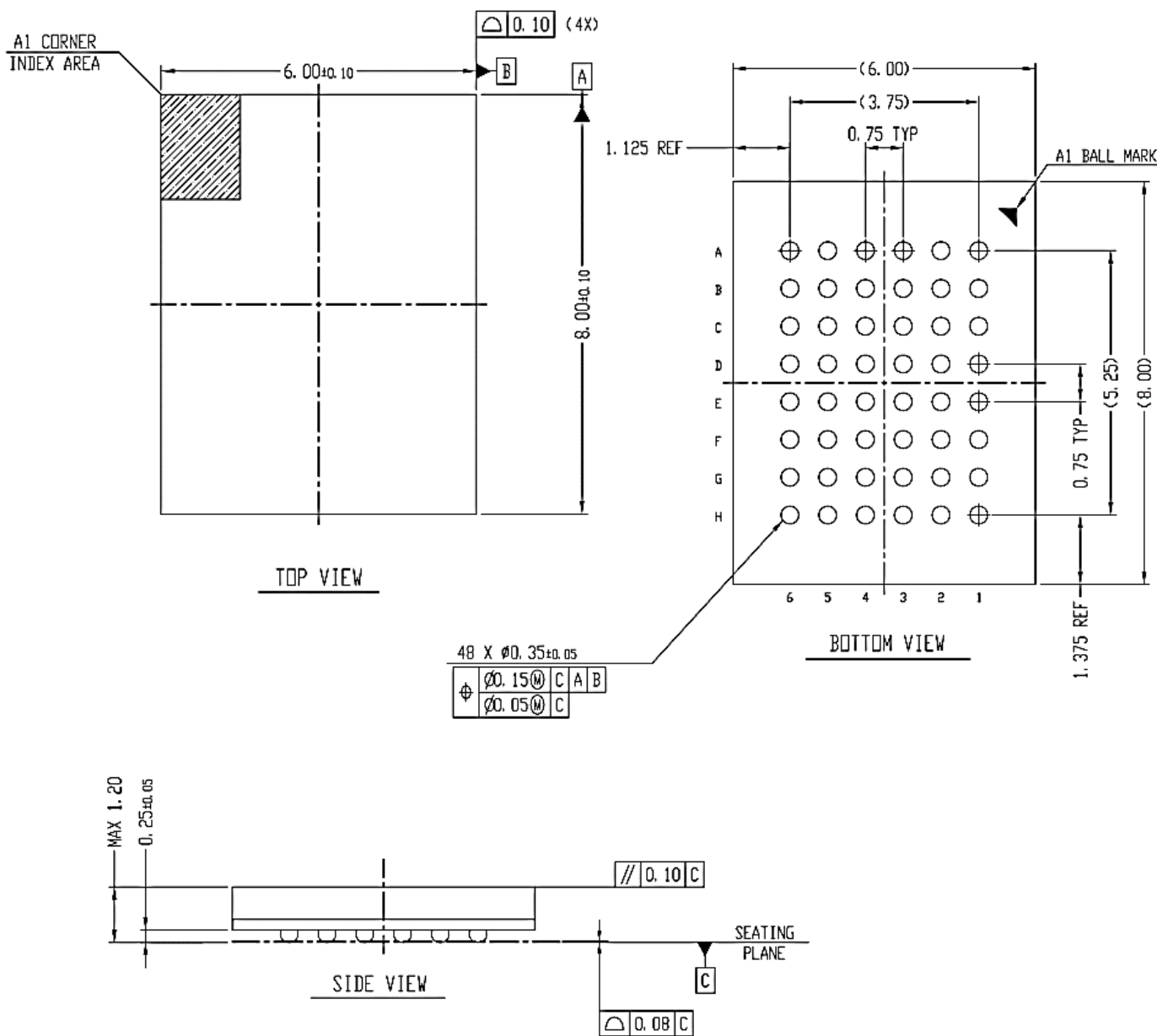
Ordering Part Numbers

Table 18 : Ordering Part Numbers

Density	Org.	Temperature	Package	Packing Material	Part Number
4Mb	x16	-40°C ~ 85°C	44TSOP2	Tray	S3R4016R1M-UI70
				Tape and Reel	S3R4016R1M-UI70T
			48FBGA	Tray	S3R4016R1M-XI70
				Tape and Reel	S3R4016R1M-XI70T
	x8	-40°C ~ 85°C	44TSOP2	Tray	S3R4008R1M-UI70
				Tape and Reel	S3R4008R1M-UI70T
			48FBGA	Tray	S3R4008R1M-XI70
				Tape and Reel	S3R4008R1M-XI70T

Package Dimension

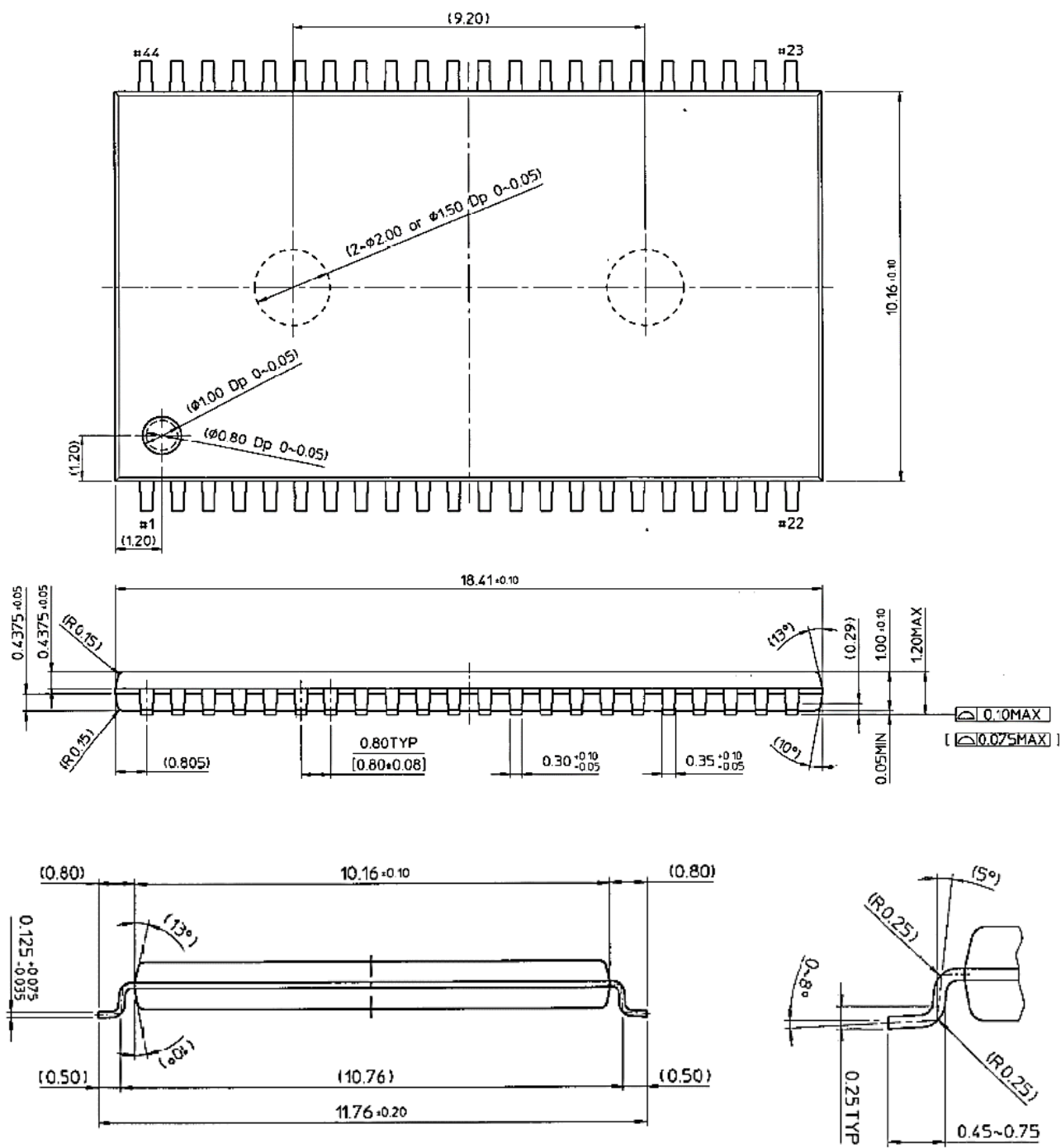
48 FBGA



[Notes]

1. All Dimensions in Millimeters
2. Solder ball Diameter is post reflow diameter
(Raw Solder ball size is ϕ 0.30mm)

44 TSOP2



[Notes]

1. Dimensions in Millimeters/Inches
2. Lead Finish : Solder Plated
3. Package dimensions refer to JEDEC MS-024

Revision History

Revision	Data	Description
0.1	Jun. 2022	Initial Release, Preliminary
0.2	Jan. 2023	1. Update the magnetic immunity parameter(Table 9) 2. Update the pin capacitance(Table 11) 3. Update thermal resistance(Table 17) 4. Change Ordering Part Numbers(Table 18) - delete commercial temperature range
1.0	Jul. 2023	1. Remove Preliminary status 2. Update DC Characteristics(Table 13)
1.1	Mar. 2024	Change Write Cycle Time (Table 15) - twc 320ns → 240ns, tcSDW 250ns → 180ns
1.2	May. 2024	The 4Mb density data sheet has been separated from the 1Mb/2Mb/4Mb/8Mb/16Mb integrated data sheet.